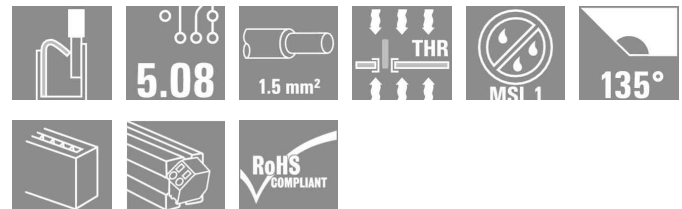


OMNIMATE Signal - series LSF
LSF-SMT 5.08/07/135 3.5SN BK TU

Weidmüller Interface GmbH & Co. KG
 Klingenbergstraße 16
 D-32758 Detmold
 Germany
 Fon: +49 5231 14-0
 Fax: +49 5231 14-292083
 www.weidmueller.com



PCB terminal for fully automatic assembly in reflow soldering (SMT), with Push In conductor connection system. Conductor inserted and slider operated in same direction (TOP). Packed in box or as tape on reel. Pin lengths optimised at 1.5 mm or 3.5 mm.

- 0.20 - 1.5 mm² (IEC) / 24 - 16 AWG (UL)
- 500 V (IEC) / 300 V (UL)
- 17.5 A (IEC) / 12 A (UL)

General ordering data

Type	LSF-SMT 5.08/07/135 3.5SN BK TU
Order No.	1885070000
Version	PCB terminal, 5.08 mm, No. of poles: 7, 135°, Solder pin length (l): 3.5 mm, tinned, Black, PUSH IN spring connection, Clamping range, rated connection, max.: 1.5 mm ² , Tube
GTIN (EAN)	4032248489732
Qty.	15 pc(s).
Product data	IEC: 500 V / 17.5 A / 0.2 - 1.5 mm ² UL: 300 V / 12 A / AWG 24 - AWG 16
Packaging	Tube

Creation date September 16, 2013 9:14:46 PM CEST

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Technical data

Dimensions and weights

Net weight	8.267 g
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System characteristics

Product family	OMNIMATE Signal - series LSF	Wire connection method	PUSH IN spring connection
Mounting onto the PCB	Reflow solder connection	Conductor outlet direction	135°
Pitch in mm (P)	5.08 mm	Pitch in inches (P)	0.2 inch
No. of poles	7	Fitted by customer	Yes
Solder pin length (l)	3.5 mm	Solder eyelet hole diameter (D)	1.1 mm
Solder eyelet hole diameter tolerance (D)+ 0,1 mm		Number of solder pins per pole	2
Stripping length	8 mm	L1 in mm	30.48 mm
L1 in inches	1.2 inch	Touch-safe protection acc. to DIN VDE 0470	IP 20
Touch-safe protection acc. to DIN VDE 57 106	Safe from finger touch		

Material data

Insulating material	LCP GF	Colour	Black
UL 94 flammability rating	V-0	CTI	≥ 175
Contact material	Cu-Leg	Contact surface	tinned
Contact base material	Cu-Leg		

Connectable conductors

Clamping range, rated connection, min.	0.13 mm ²	Clamping range, rated connection, max.	1.5 mm ²
Wire connection cross section AWG, min.	AWG 24	Wire connection cross section AWG, max.	AWG 16
Solid, min. H05(07) V-U	0.2 mm ²	Solid, max. H05(07) V-U	1.5 mm ²
Flexible, min. H05(07) V-K	0.2 mm ²	Flexible, max. H05(07) V-K	1.5 mm ²
w. wire end ferrule, DIN 46228 pt 1, min.	0.25 mm ²	w. wire end ferrule, DIN 46228 pt 1, max.	1.5 mm ²
w. plastic collar ferrule, DIN 46228 pt 4, min.	0.25 mm ²	w. plastic collar ferrule, DIN 46228 pt 4, max.	0.75 mm ²

DIN IEC rating data

Rated current, min. no. of poles (TU=20°C)	17.5 A	Rated current, max. no. of poles (Tu=20°C)	17.5 A
Rated current, number of poles (Tu=40°C), min	17.5 A	Rated current, number of poles (Tu=40°C), max.	15 A
Rated voltage for surge voltage class pollution degree II/2	500 V	Rated voltage for surge voltage class pollution degree III/2	320 V
Rated voltage for surge voltage class pollution degree III/3	250 V	Rated impulse voltage for surge voltage class pollution degree II/2	4 kV
Rated impulse voltage for surge voltage class pollution degree III/2	4 kV	Rated impulse voltage for surge voltage class contamination degree III/3	4 kV
Short-time withstand current resistance	3 x 1 s with 80 A		

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Technical data

CSA rating data

Institute (CSA)



Rated voltage (Use group B)

300 V

Rated current (use group B) 10 A

Rated voltage (use group D) 300 V

Rated current (use group D) 10 A

Wire cross-section, AWG, min. AWG 24

Wire cross-section, AWG, max. AWG 16

UL 1059 rating data

Rated voltage (use group B) 300 V

Rated current (use group B) 12 A

Rated voltage (use group D) 300 V

Rated current (use group D) 10 A

Wire cross-section, AWG, min. AWG 24

Wire cross-section, AWG, max. AWG 16

Classifications

ETIM 3.0

EC001284

UNSPSC

30-21-18-11

eClass 5.1

27-26-11-01

eClass 6.2

27-26-11-01

eClass 7.1

27-44-04-01

Notes

Notes

- Additional push button colours on request
- Rated current related to rated cross-section & min. No. of poles.
- Wire end ferrule without plastic collar to DIN 46228/1
- P on drawing = pitch
- Operating force of slider max. 40 N
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- Crimping shape "A" for wire end ferrules with PZ 6/5 crimping tool are recommended for the largest cable sizes.

Approvals

Approvals



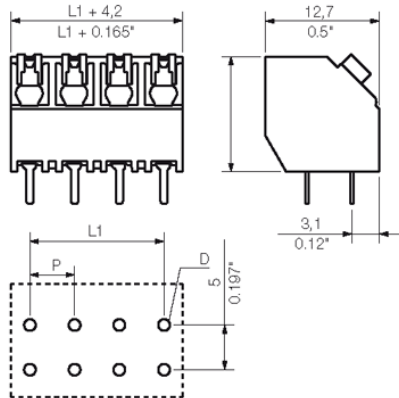
ROHS

Conform

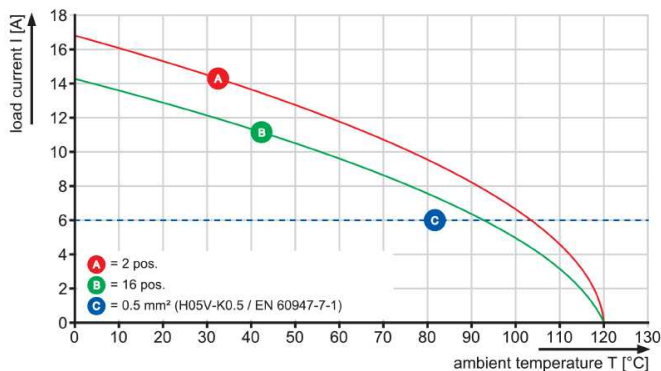
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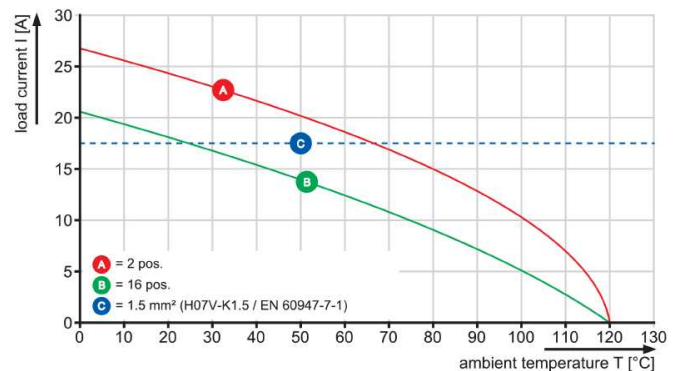
Drawings



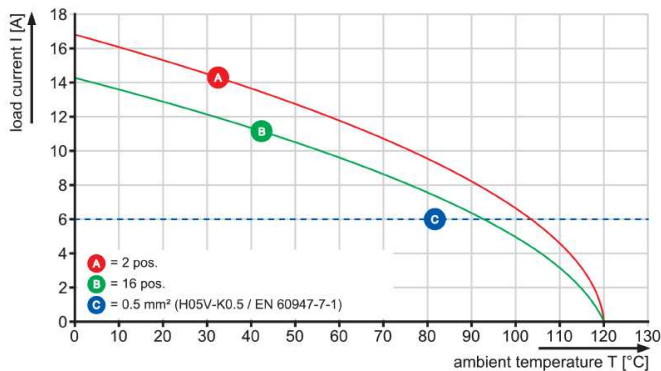
LSF-SMT 5.08/./135 1.5



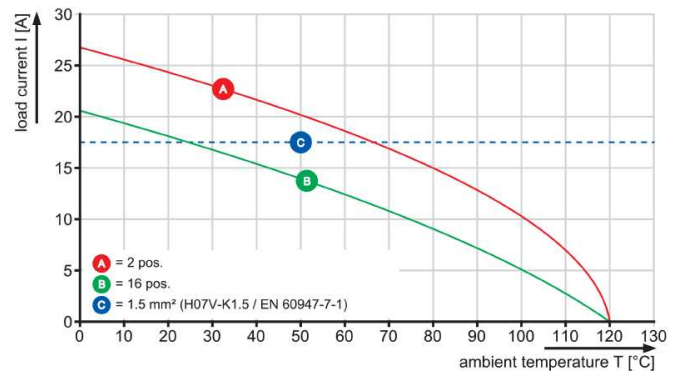
LSF-SMT 5.08/./135 1.5



LSF-SMT 5.08/./135 3.5



LSF-SMT 5.08/./135 3.5



Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16

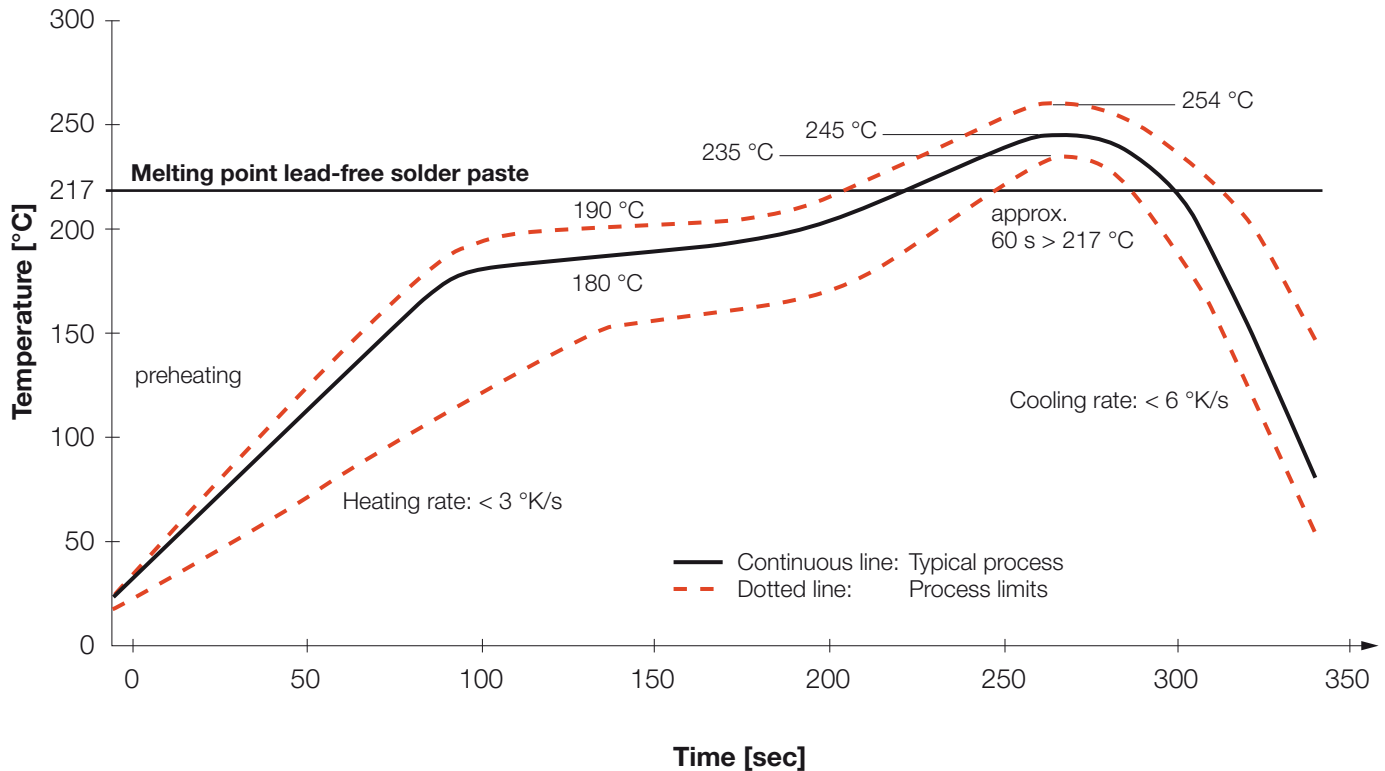
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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.

